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Application No.: 09/864,055
Docket No.: JIAN0094-C1-CIP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

Ellis Lee et al.

Serial No. : 09/864,055

Filed : May 23, 2001

For : Bonding Pad Structure and Method
for Making Same

Examiner : Nguyen, Cuong Quang

Art Unit : 2811

12/4/03
Shm HPRELIMINARY AMENDMENTCommissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This amendment is filed with a Request for Continued Examination. Please enter the following amendments and consider the following remarks.